

BAS20HT1

Preferred Device

High Voltage Switching Diode

- Device Marking: JS

MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V_R	Continuous Reverse Voltage	250	Vdc
I_F	Peak Forward Current	200	mAdc
$I_{FM}(\text{surge})$	Peak Forward Surge Current	625	mAdc

THERMAL CHARACTERISTICS

Symbol	Characteristic	Max	Unit
P_D	Total Device Dissipation FR-5 Board,* $T_A = 25^\circ\text{C}$ Derate above 25°C	200	mW
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	1.57	$\text{mW}/^\circ\text{C}$
T_J, T_{stg}	Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

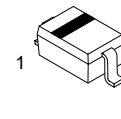
*FR-5 Minimum Pad



ON Semiconductor™

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HIGH VOLTAGE SWITCHING DIODE



SOD-323
CASE 477
STYLE 1

MARKING DIAGRAM



JS = Specific Device Code
M = Date Code

ORDERING INFORMATION

Device	Package	Shipping
BAS20HT1	SOD-323	3000/Tape & Reel

Preferred devices are recommended choices for future use and best overall value.

BAS20HT1

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Voltage Leakage Current ($V_R = 200\text{ Vdc}$) ($V_R = 200\text{ Vdc}$, $T_J = 150^\circ\text{C}$)	I_R	– –	1.0 100	μAdc
Reverse Breakdown Voltage ($I_{BR} = 100\ \mu\text{Adc}$)	$V_{(BR)}$	250	–	Vdc
Forward Voltage ($I_F = 100\ \text{mA dc}$) ($I_F = 200\ \text{mA dc}$)	V_F	– –	1000 1250	mV
Diode Capacitance ($V_R = 0$, $f = 1.0\ \text{MHz}$)	C_D	–	5.0	pF
Reverse Recovery Time ($I_F = I_R = 30\ \text{mA dc}$, $R_L = 100\ \Omega$)	t_{rr}	–	50	ns

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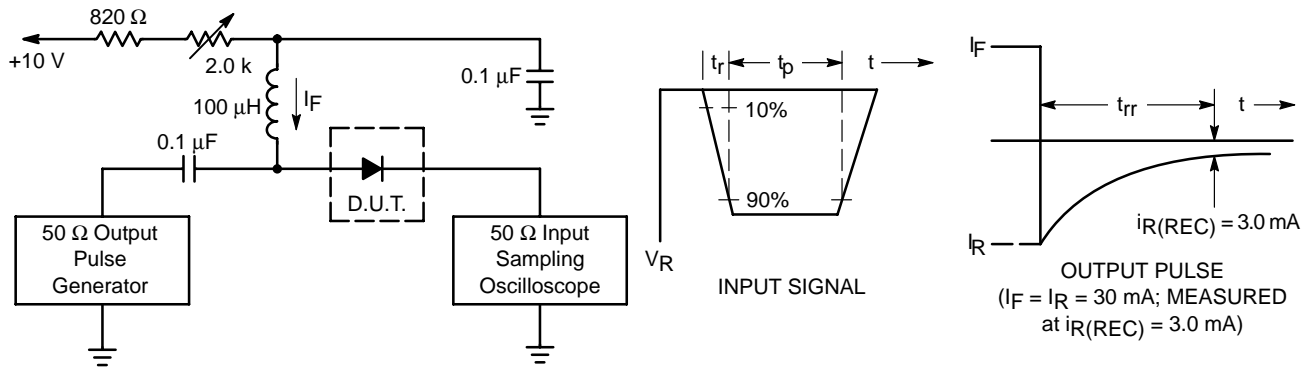


Figure 1. Recovery Time Equivalent Test Circuit

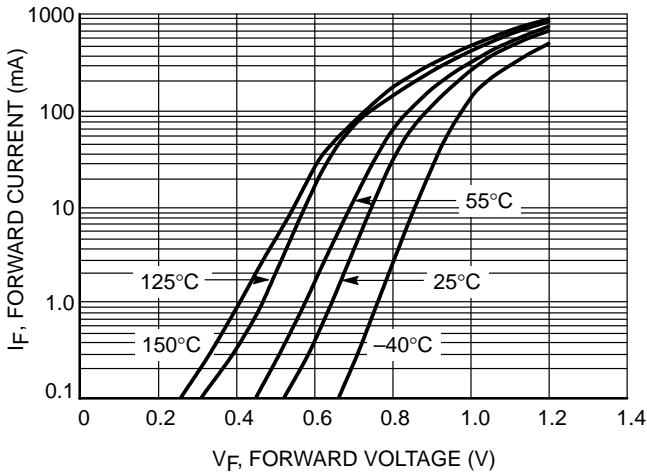


Figure 2. Forward Current

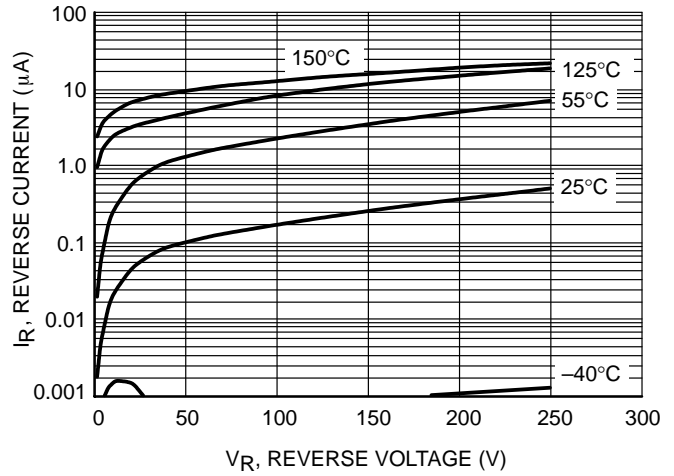


Figure 3. Leakage Current

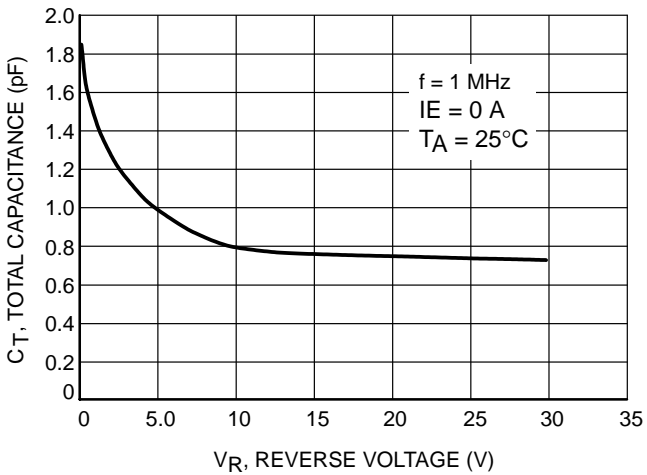


Figure 4. Total Capacitance

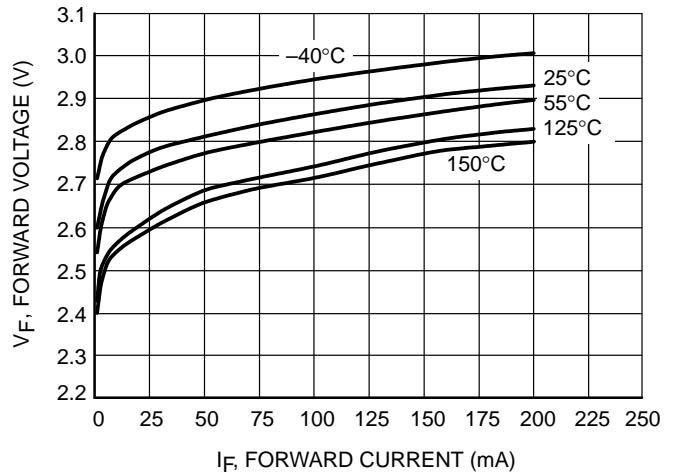
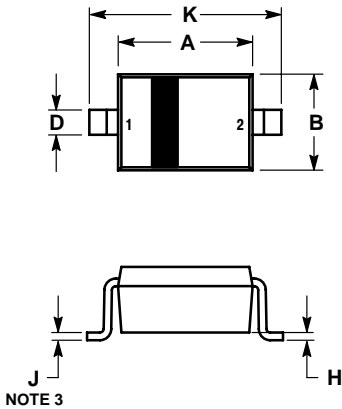


Figure 5. Forward Voltage

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PACKAGE DIMENSIONS

SOD-323
CASE 477-02
ISSUE B



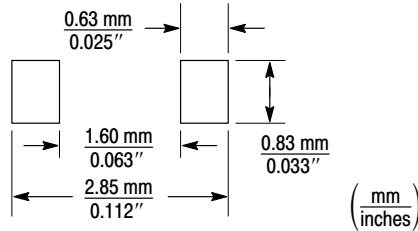
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.60	1.80	0.063	0.071
B	1.15	1.35	0.045	0.053
C	0.80	1.00	0.031	0.039
D	0.25	0.40	0.010	0.016
E	0.15 REF		0.006 REF	
H	0.00	0.10	0.000	0.004
J	0.089	0.177	0.0035	0.0070
K	2.30	2.70	0.091	0.106


STYLE 1:

1. CATHODE
2. ANODE



SOD-323
Soldering Footprint

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